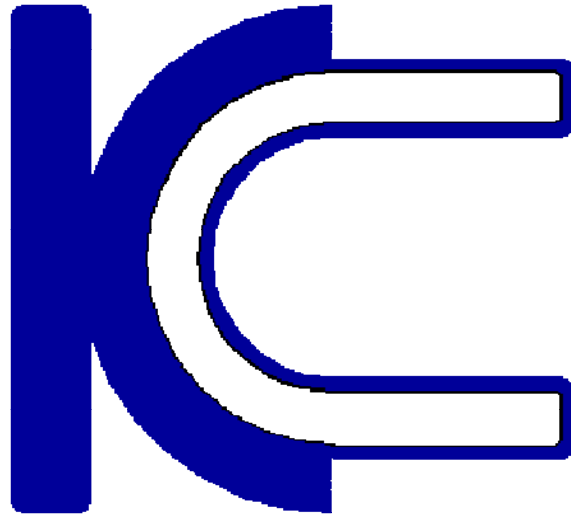


KING CORE ELECTRONICS INC.



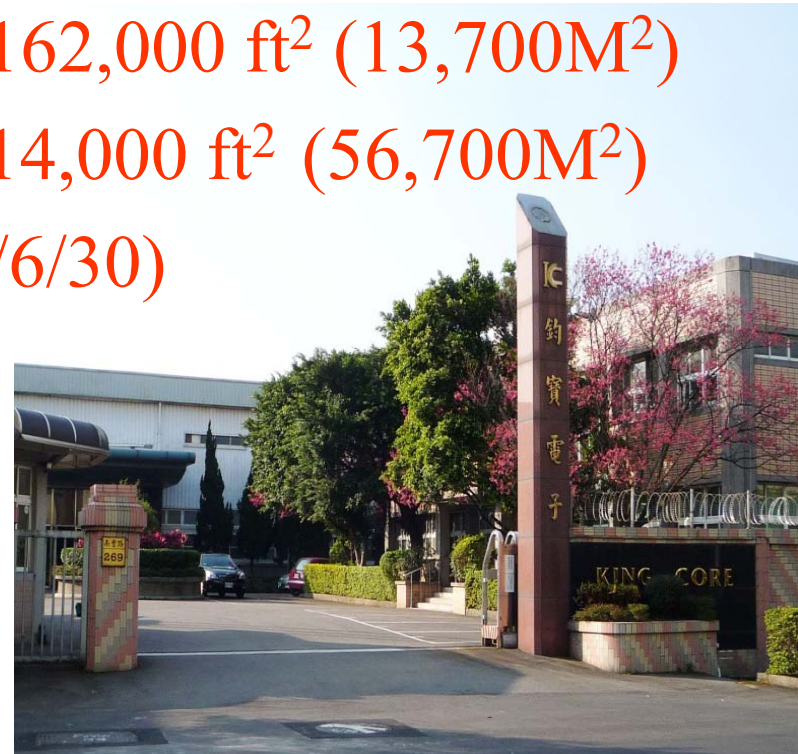
Your Best EMI Solution Partner

A Company with Health, Happiness and Prospect



COMPANY INTRODUCTION

- Date of Establishment: **Nov. 29, 1986.**
- Location: **Taiwan Taoyuan, 162,000 ft² (13,700M²)**
China Suzhou, 614,000 ft² (56,700M²)
- Capital: **USD 28.9 M. (2019/6/30)**
- President: Henry Yang
- General Manager: Rex Chen
- Employees: **~400 Persons**





COMPANY HISTORY

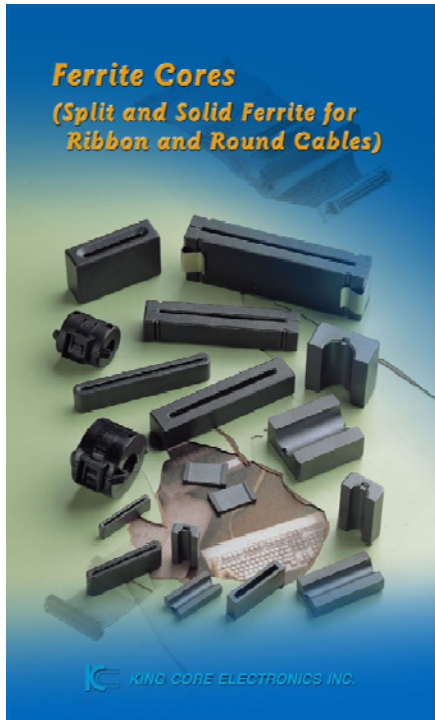
- ✦ 1986 : Established to produce **ferrite cores**
- ✦ 1995 : The second factory established to produce **SMT multilayer chip beads / inductors.**
- ✦ 1996 : **ISO 9000** certificated
- ✦ 1999 : Foundation Laying of King Core – **Suzhou China**
- ✦ 2001 : To be listed company on **OTC (Stock Code : 6155)**
- ✦ 2003 : The third factory established to produce **SMT precision chokes and coils.**
- ✦ 2006 : To be listed company on **TWSE**
- ✦ 2008 : **ISO 14000** certificated
- ✦ 2009 : To be **SONY Green Partner**
- ✦ 2009 : **IECQ QC080000** certificated
- ✦ 2012 : **TS16949** certificated
- ✦ 2013 : To invest in developing **GHz filter**
- ✦ 2014 : To invest in developing **mini power choke / inductor**
- ✦ 2016 : **Solar Power** Generation at Pingjhen site : **417.6KW, 500K degrees/year**
- ✦ 2017 : To invest in developing **LTCC BPF, LPF, Diplexer**





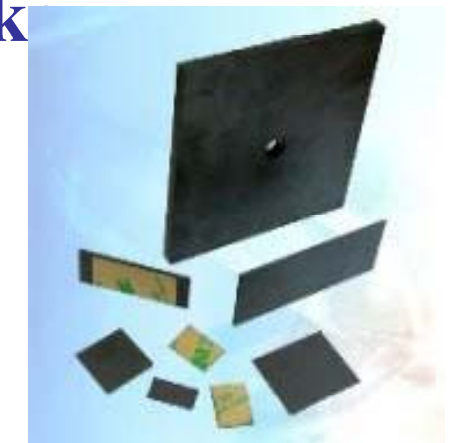
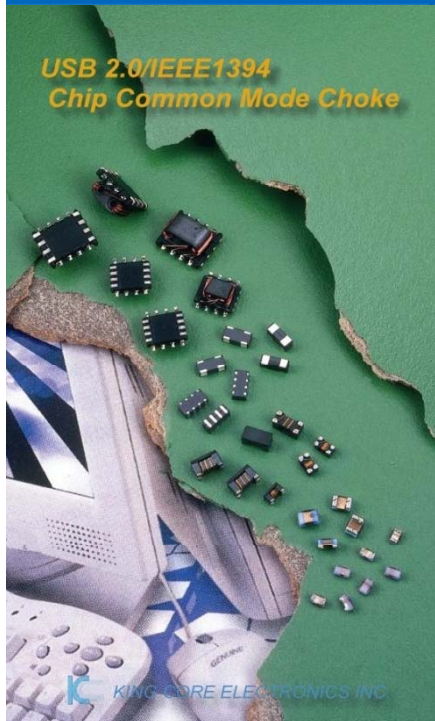
AWARD & HONOR

- 1997 : **The first computerized ferrite factory in Taiwan** and also the example factory by government Taiwan Small and Medium Enterprise Administration Ministry of Economic Affairs.
- 1999 : Awarded “**the Rising Star**” by Government the best Medium and small enterprises.
- 2000 : Been Awarded “ **The Achievement Price of Industrial Pollution Prevention and Waste Control**” by Ministry of Economic Affairs, ROC
- 2000 : Been Awarded “**The Best Center-satellite Factory of Environment Management**” by Compal Computer Corp.
- 2001 : KC’s Founder and President, Mr. Yang, been awarded “**24th Annual Models of Chinese Youth Entrepreneur**”
- 2002 : Been awarded by Asus Computer Inc as the “**2001 the Best Cooperative Supplier**”
- 2002 : Been selected by Global Views Monthly as the **24th Best-Performance Company in Info Tech Top 200 of Taiwan**
- 2005 : Been selected by Deloitte as the **Top 500 of Asia Tech. company**
- 2007~2018 : **Hitachi best performance vendor award.**

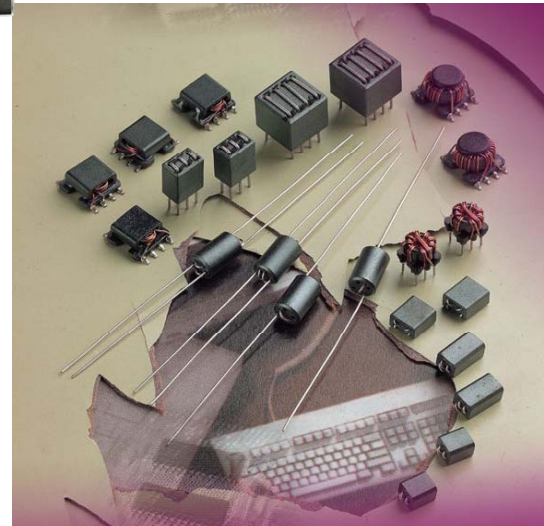


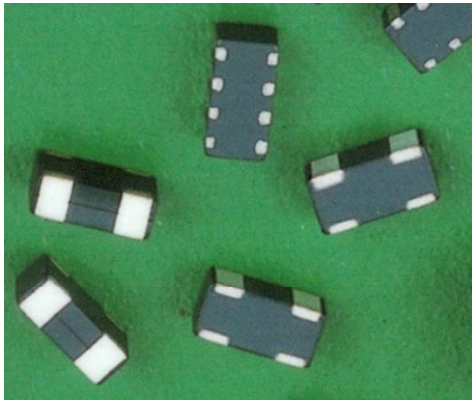
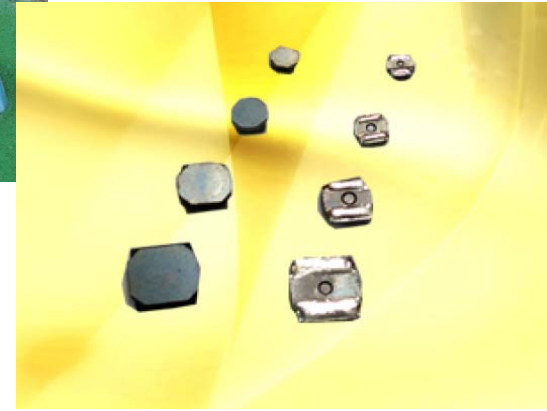
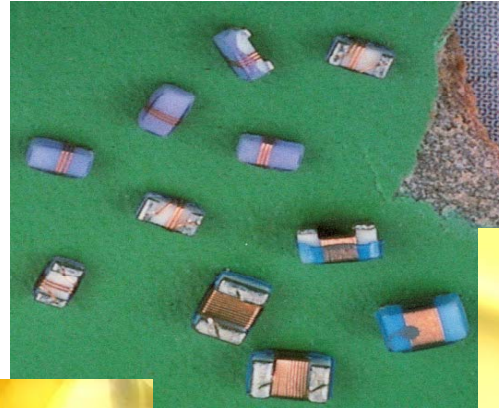
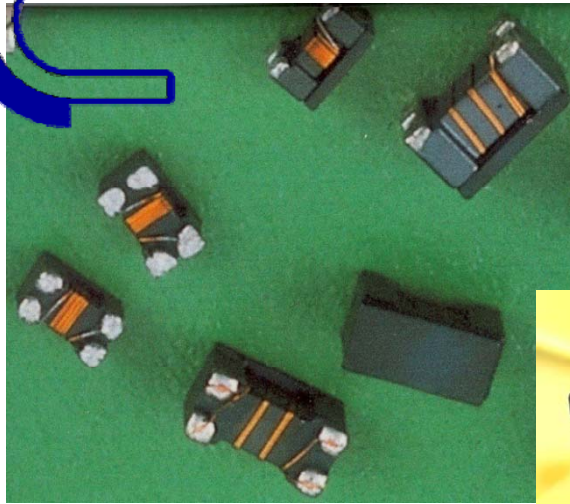
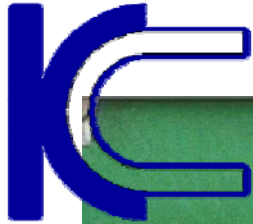
MAIN PRODUCTS

- **EMI Suppression Ferrite Cores**
 - **500 tons/ month**
- **SMT Multilayer Chip Beads & Inductors**
 - **300~500 kkpcs/ month(0402/0603)**
- **Wound Chip inductor & Choke**
 - **100~150 kkpcs/ month**
- **Ferrite Absorber**
 - **1 kkpcs/ month**



2019/10/22

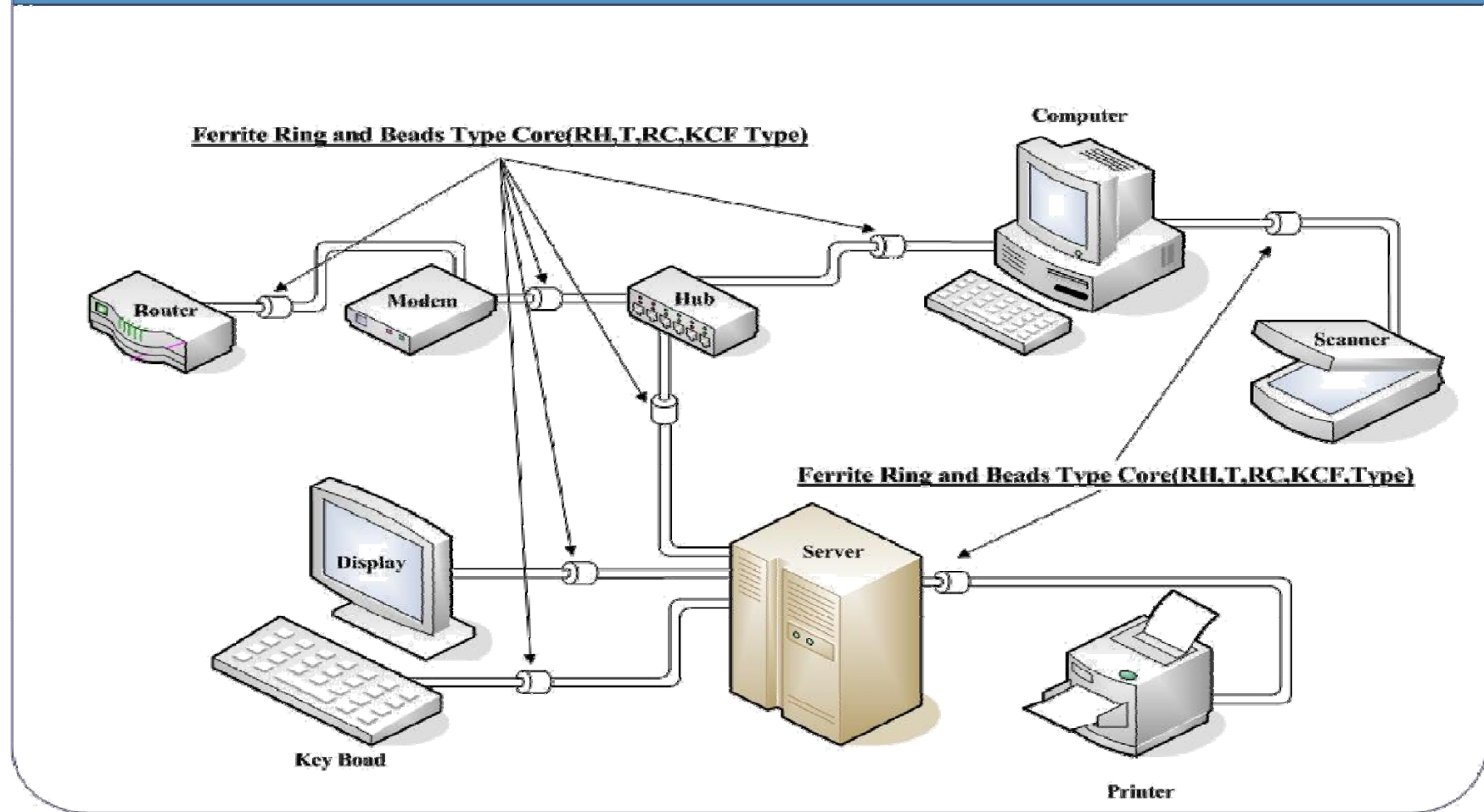






KC EMI Suppression Core Application

An Illustration of How to Apply EMI Ferrite Core on Cable





KC EMI Filter Application

CPU data bus之對策
 可:採用**FBM-10 series**
 10 - 70 ohm bead

Comm 1, 2 介面之EMI 對策
 可:採用**FBM-10 series**
 70 - 220 ohm bead

Modem 電話介面之EMI 對策
 可:採用**FBM-11 series**
 600 - 1000 ohm bead

IC 電源 Vcc+ in之對策
 可:採用**FBM...A series**
 耐大電流 120 ohm bead

Print Port介面之EMI 對策
 可:採用**FBM-11 series**
 70 - 300 ohm bead

DC in 電源input之對策
 可:採用**FBM...A series**
 耐大電流 120 ohm bead

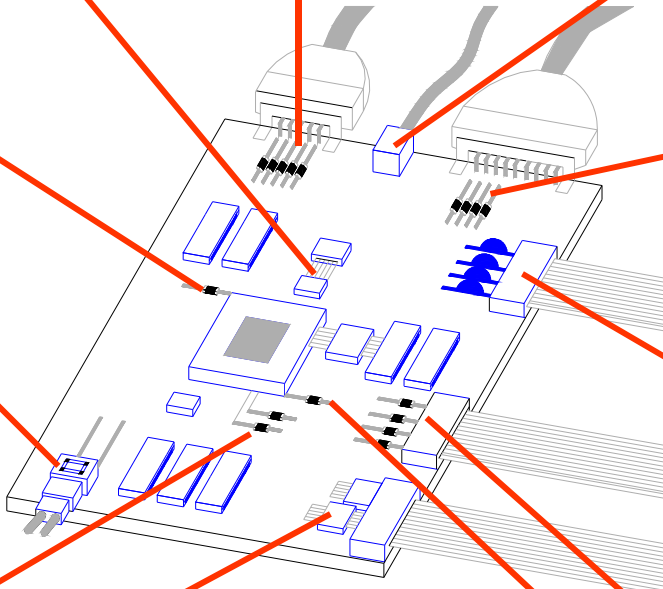
Video out or LVDS介面之 EMI對策
 可:採用**FBM-10 series**
 30 - 120 ohm bead

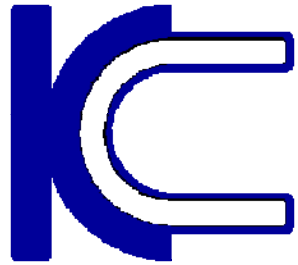
Clock Generator 之對策
 可:採用**FBM-10 series**
 10 - 70 ohm bead

IEEE 1394 or USB or LAN 介面之EMI對策
 可:採用**WCM series** 90-220 ohm common choke

IC Grounding 接地之對策
 可:採用**FBM-11 series**
 120 - 600 ohm bead

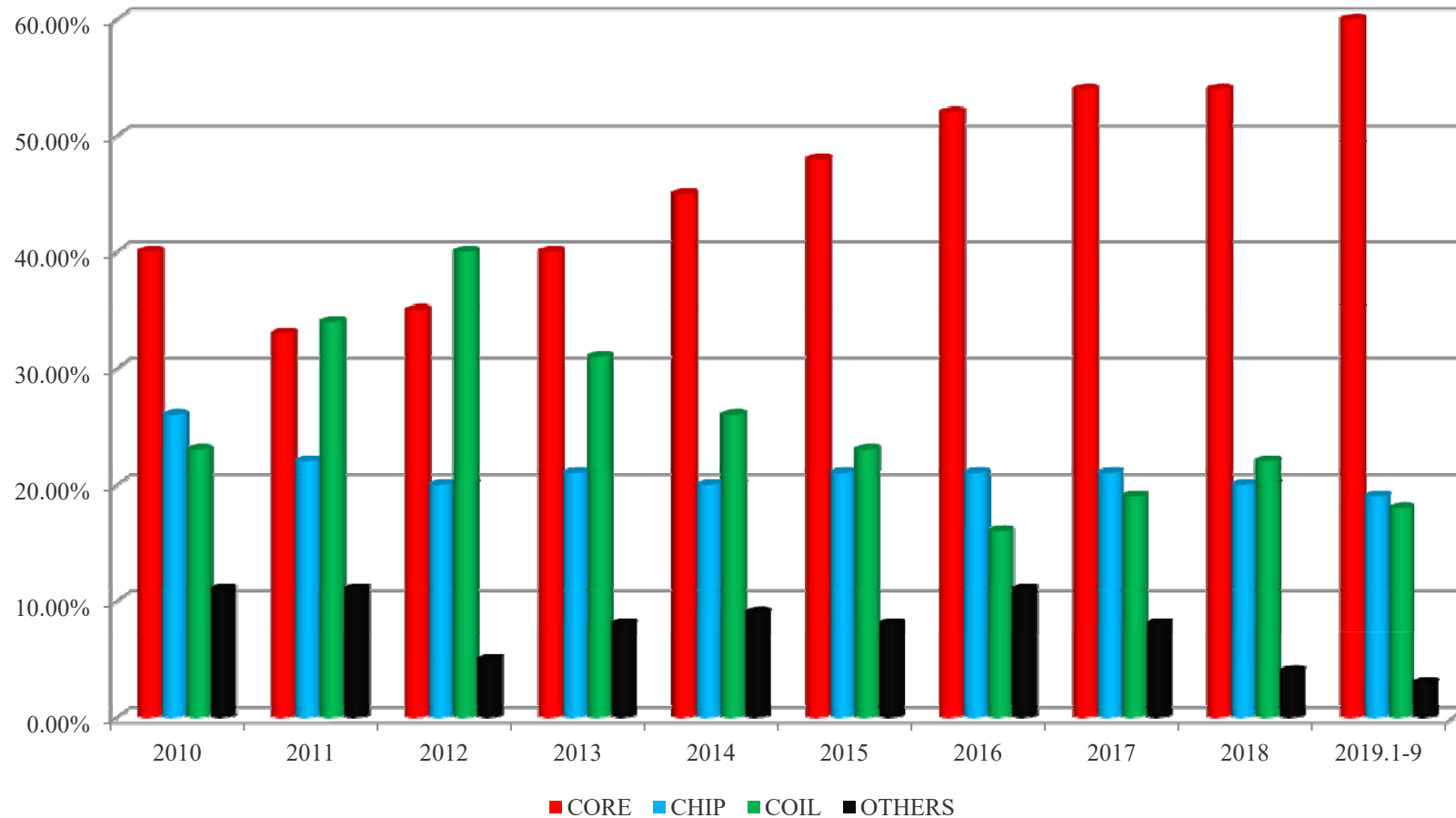
HDD or CD-ROM介面之 EMI對策
 可:採用**FBM-10 series**
 10 - 70 ohm bead

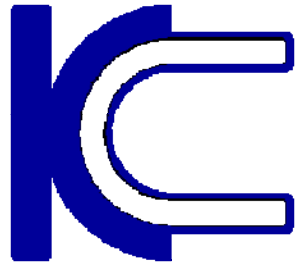




Proportion of Product Type

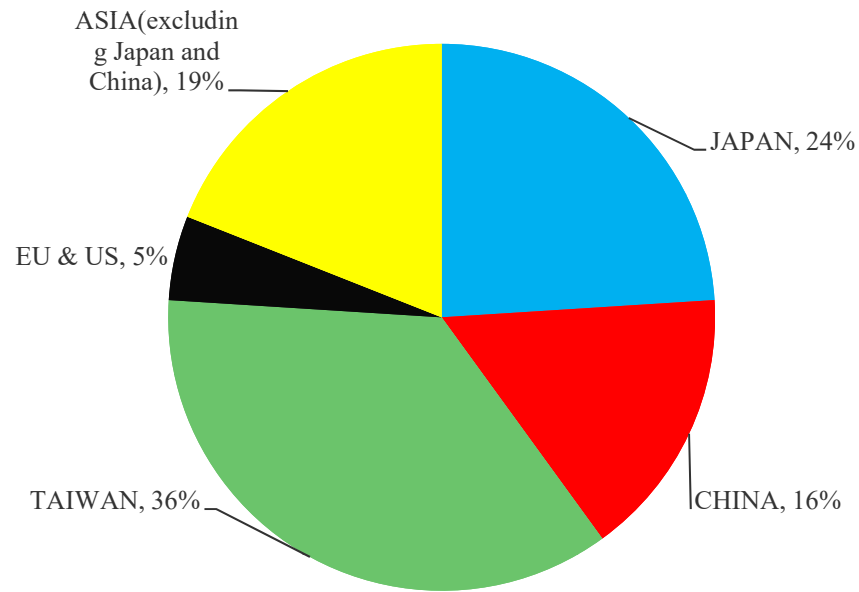
2019.1~9
CORE : 60%
CHIP : 19%
COIL : 18%
OTHERS : 3%



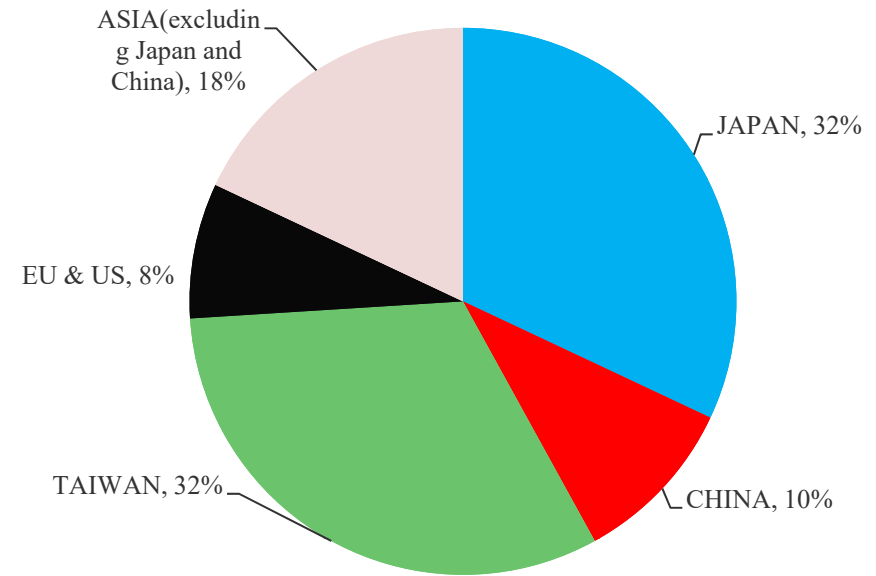


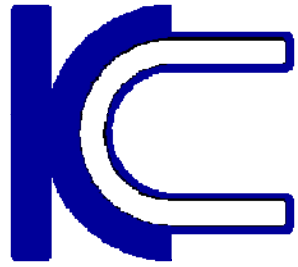
Proportion of Customer Area

2018

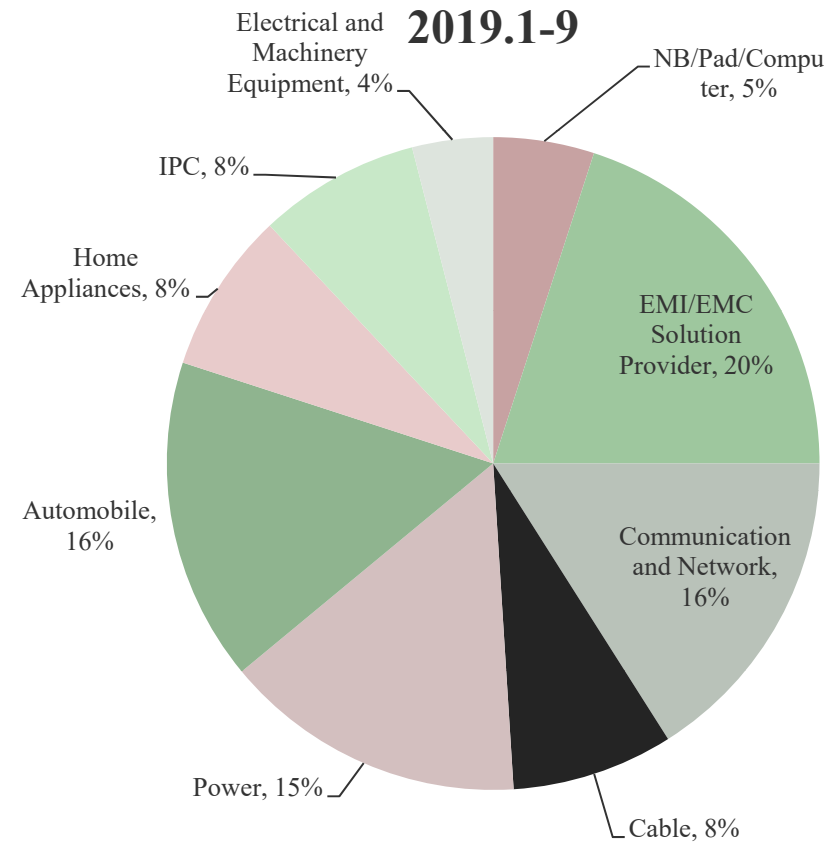
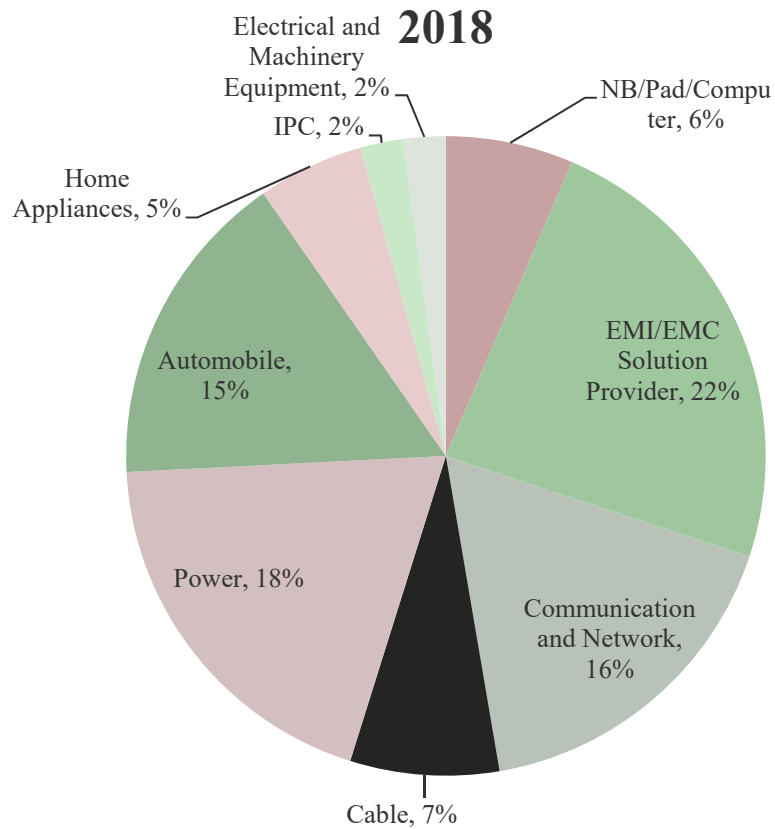


2019



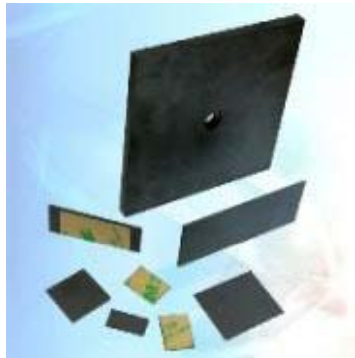
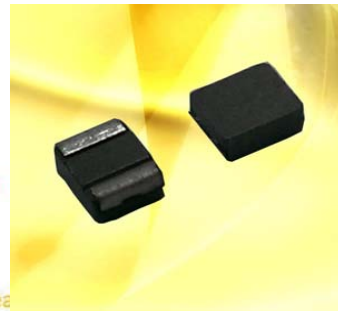
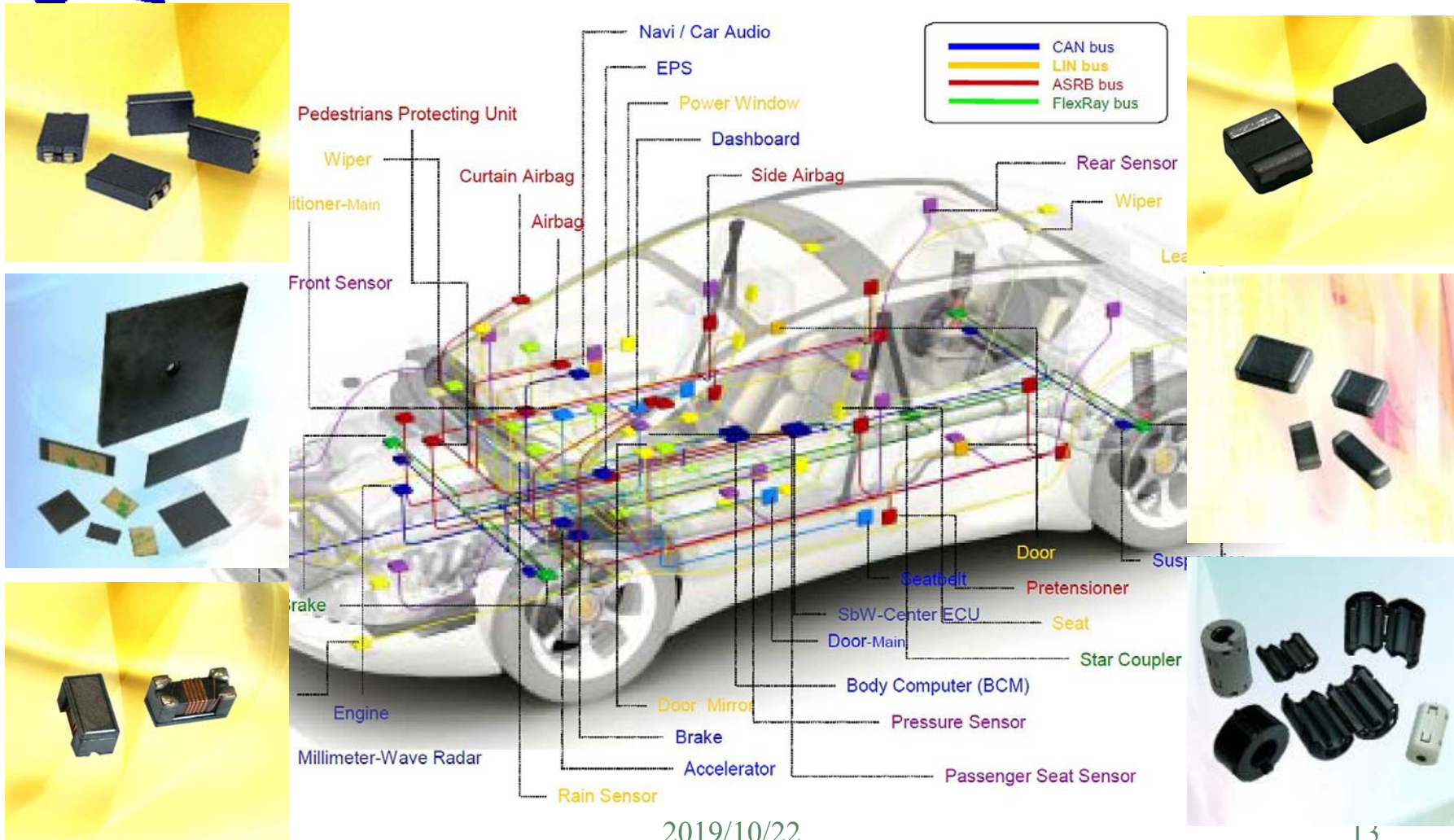


Proportion of Customer Application

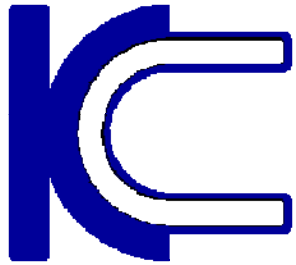




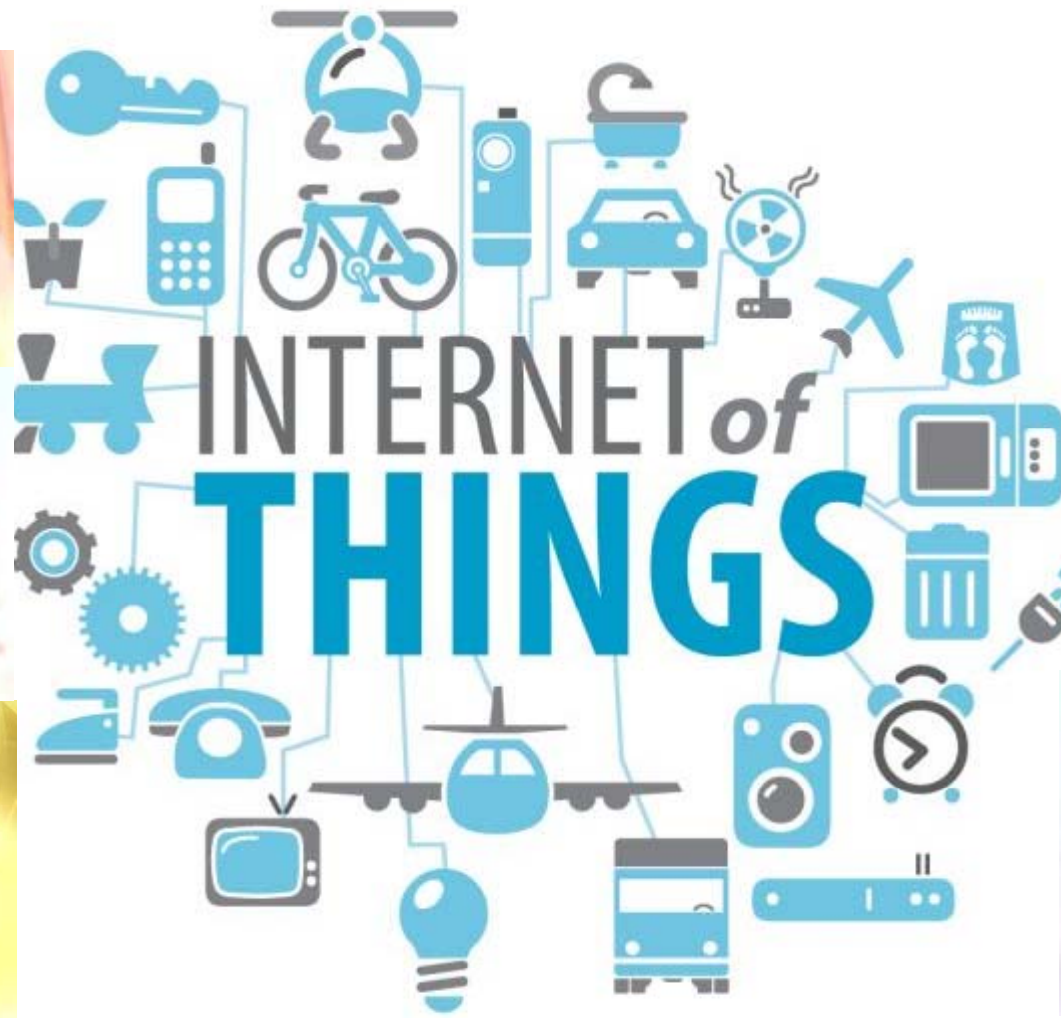
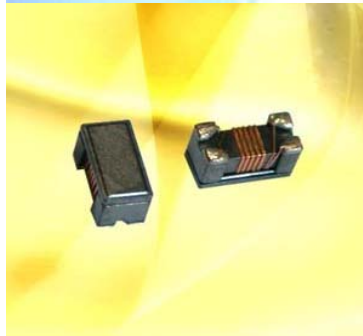
Automobile Electronics Application



2019/10/22

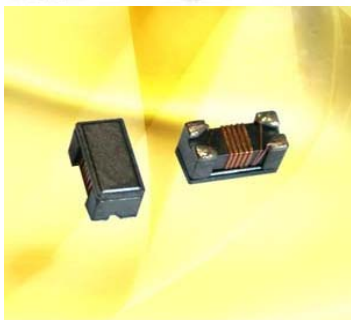
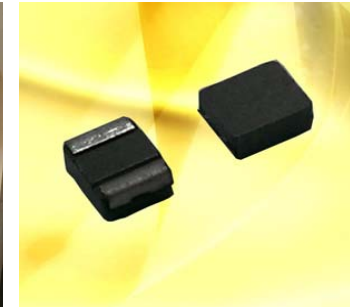


Communication and Network Application





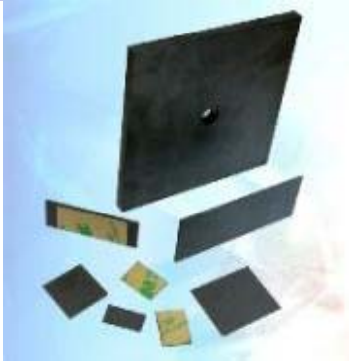
Home Appliances and IPC

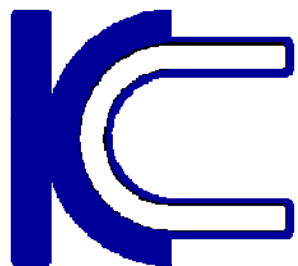


2019/10/22



Power Application





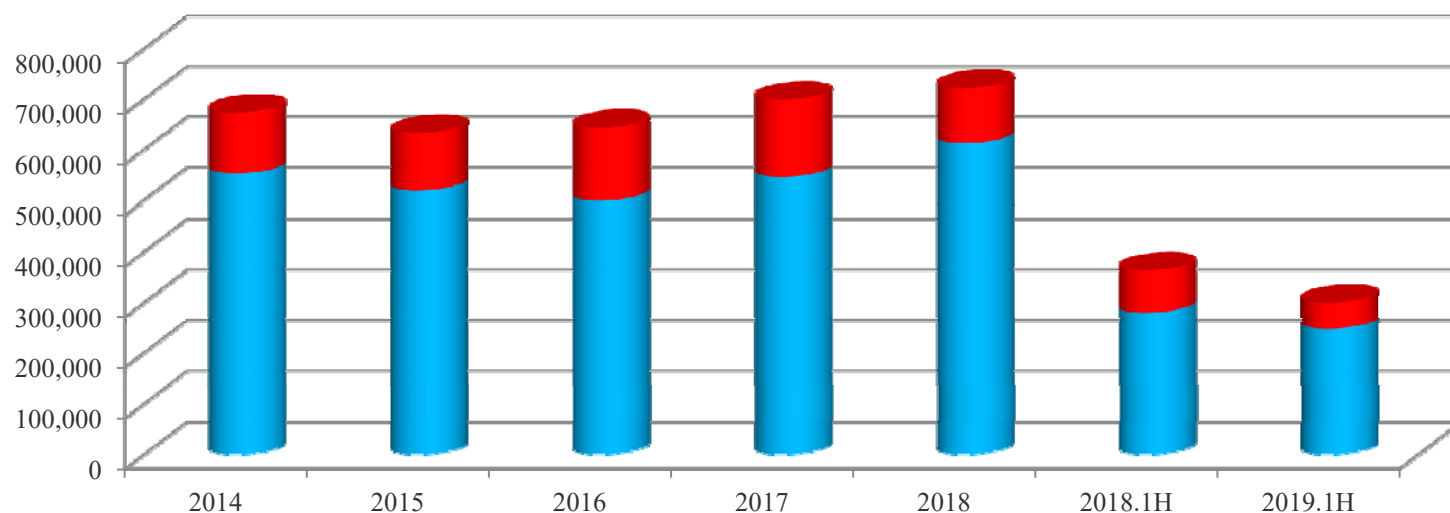
Turnover over the years

2019.1~9 : 479,005

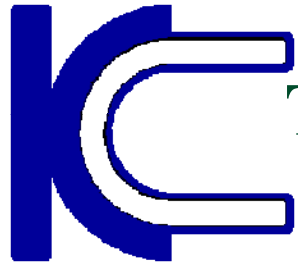
YoY : -13%

NTD : K

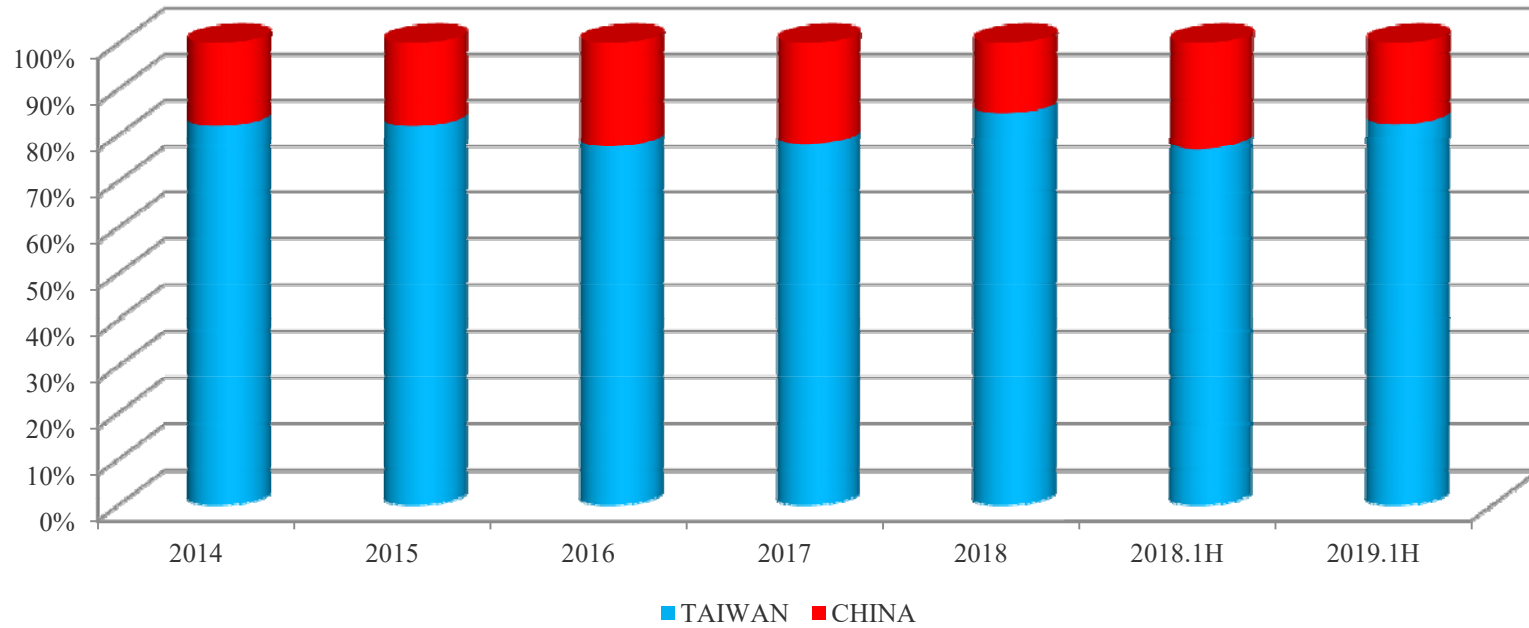
■ TAIWAN ■ CHINA



	2014	2015	2016	2017	2018	2019.1H	2019.1~9
Sales	673,016	632,332	642,745	698,467	722,186	299,835	479,005



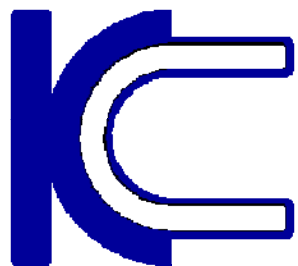
Turnover proportion in Taiwan and Suzhou



	2014	2015	2016	2017	2018	2018.1H	2019.1H
Taiwan	82%	82%	78%	78%	85%	77%	82%
China	18%	18%	22%	22%	15%	23%	18%

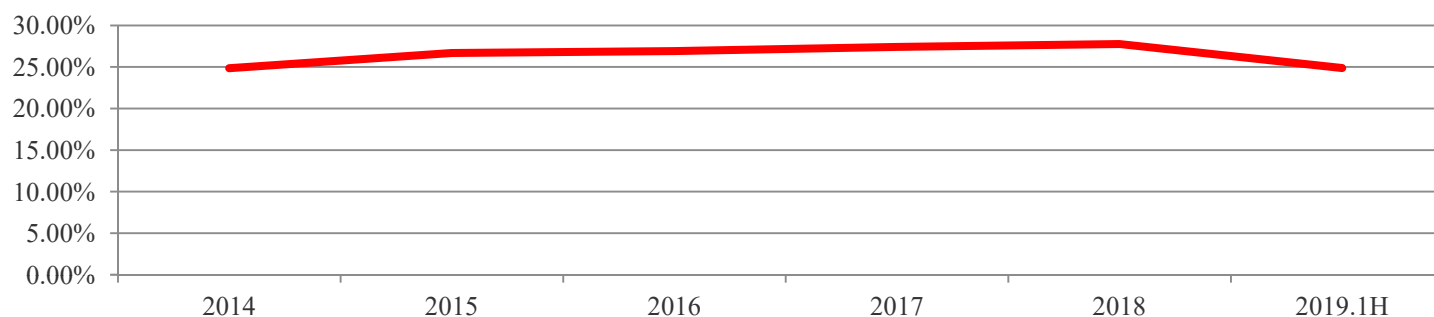
2019/10/22

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Performance

Gross Margin(%)



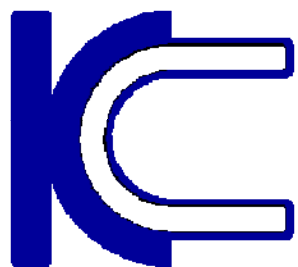
Unit : NTD, K

	2014	2015	2016	2017	2018	2019.1H
Net Revenue	673,016	632,332	642,745	698,467	722,186	299,835
Gross Profit	167,308	168,718	172,964	191,501	200,491	74,604
Gross Margin(%)	24.86%	26.68%	26.91%	27.42%	27.76%	24.88%
Profit before tax	140,547	122,163	98,105	43,480	158,602	69,311
Profit for the period	121,461	104,086	82,557	42,957	127,497	58,901
ROE(%)	8.18	7.05	5.8	3.11	9.24	4.2
EPS (NT Dollar)	1.45	1.22	0.96	0.5	1.48	0.68

Note 1: Above financial information has been audited by CPA.

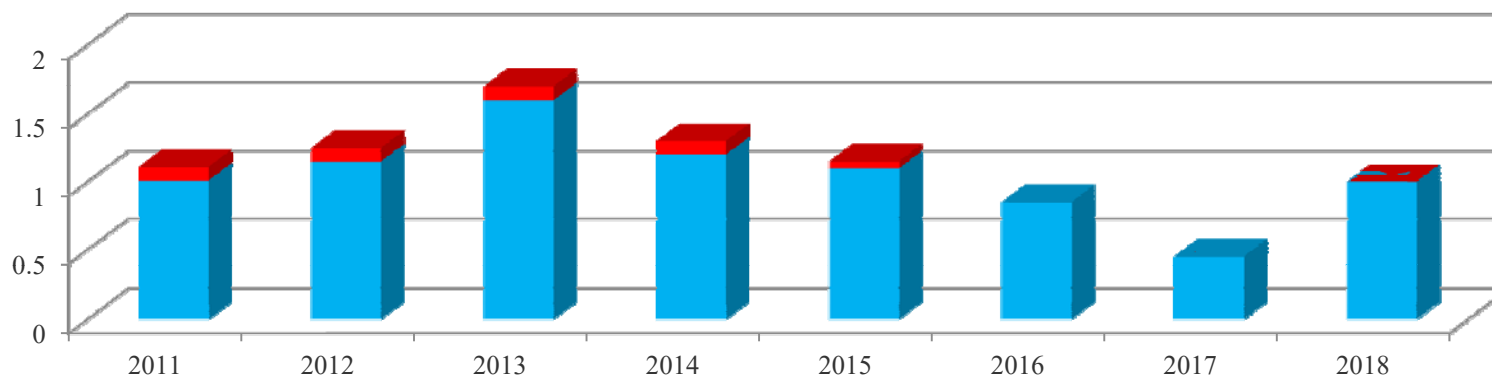
Note 2 : Adopting International Financial Reporting Standards since year 2013.

2019/10/22



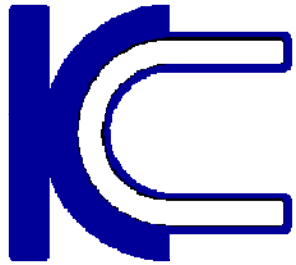
Dividend

■ 每股股利(現金) Dividend(cash) ■ 每股股利(股票) Dividend(stock)



	2011	2012	2013	2014	2015	2016	2017	2018
Basic earnings per share (NT Dollar)	0.87	1.4	1.45	1.45	1.22	0.96	0.5	1.48
Dividend (Cash)	1.01	1.15	1.6	1.2	1.1	0.85	0.45	1.0
Dividend (Stock)	0.1	0.1	0.1	0.1	0.05	0	0	0
Dividend (Total)	1.11	1.25	1.7	1.3	1.15	0.85	0.45	1.0
Payment ratio	127.59%	89.29%	117.24%	89.66%	94.26%	88.43%	90.27%	67.68%

Note :Employee bonus as expenses since year 2008.



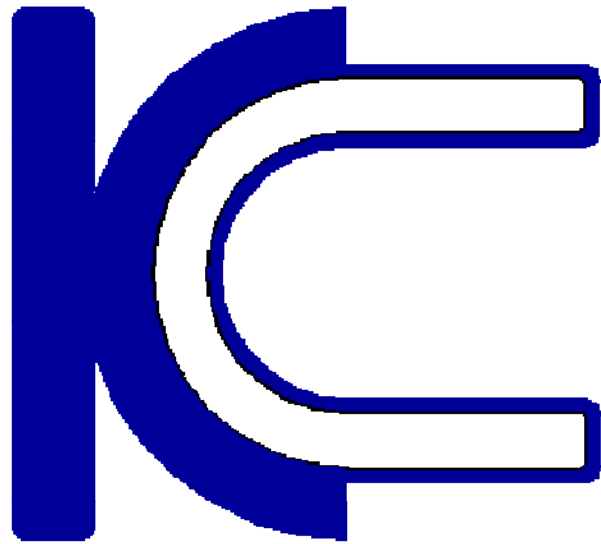
KC Product Development Roadmap

Product Target	Major Knowhow	Market Application
GHz Common Mode Filter / Choke	Precision and patent LTCC design and manufacturing	5G, Ultra-high speed differential signal interface such as Common Mode, BPF, LPF and Diplexer
GHz impedance suppression component in Multilayer chip design and material	Material composition, inner circuit design, precision printing technique	5G, GHz chip suppressor for EMI/RFI solution application
EMI suppression absorber ferrite material	Material composition, pressing technique, sintering technique	Automotive Electronics, 5G, NFC, WPC, EMI/RFI shielding tool, EMI suppression component
Higher current multilayer chip bead	Material composition, inner circuit design, lamination & sintering technique	Automotive Electronics, 5G, High current 3C product's EMI & power solution
Mini power choke	Material composition, inner circuit design, lamination & winding technique	Automotive Electronics, Miniaturization 3C product's EMI & power solution

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鈞寶電子工業股份有限公司
KING CORE ELECTRONICS INC.



Thanks for your attending